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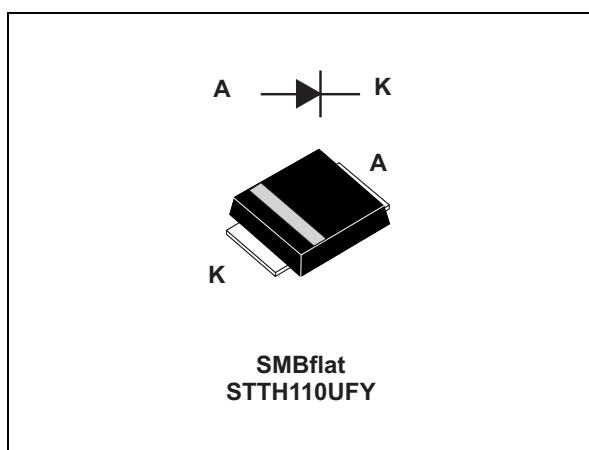
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# STTH110-Y

## Automotive high voltage ultrafast rectifier

Datasheet - production data



### Features

- Very low conduction losses
- Negligible switching losses
- Low forward and reverse recovery times
- High junction temperature
- AEC-Q101 qualified
- ECOPACK<sup>®</sup>2 compliant component

### Description

The STTH110-Y, which is using ST's new 1000 V planar technology, is especially suited for switching mode base drive and transistor circuits.

The device is also intended for use as a free-wheeling diode in power supplies and other power switching applications in automotive functions.

**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	1 A
$V_{RRM}$	1000 V
$T_{j(max)}$	175 °C
$V_F (typ)$	0.98 V
$T_{rr} (typ)$	52 ns

Characteristics

STTH110-Y

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at T<sub>j</sub> = 25 °C, unless otherwise specified)**

Symbol	Parameter	Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage	1000	V
I <sub>F(AV)</sub>	Average forward current	T <sub>L</sub> = 140 °C δ = 0.5	1 A
I <sub>FSM</sub>	Forward Surge current	t <sub>p</sub> = 8.3 ms	20 A
T <sub>stg</sub>	Storage temperature range	-65 to + 175	°C
T <sub>j</sub> <sup>(1)</sup>	Operating temperature range	-40 to + 175	°C

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
R <sub>th(j-l)</sub>	Junction to lead	20	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>		5	μA
		T <sub>j</sub> = 125 °C		1		
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 1 A		1.7	V
		T <sub>j</sub> = 150 °C		0.98	1.42	

1. Pulse test: t<sub>p</sub> = 5 ms, δ < 2%

2. Pulse test: t<sub>p</sub> = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 1.20 \times I_{F(AV)} + 0.225 I_F^2_{(RMS)}$$

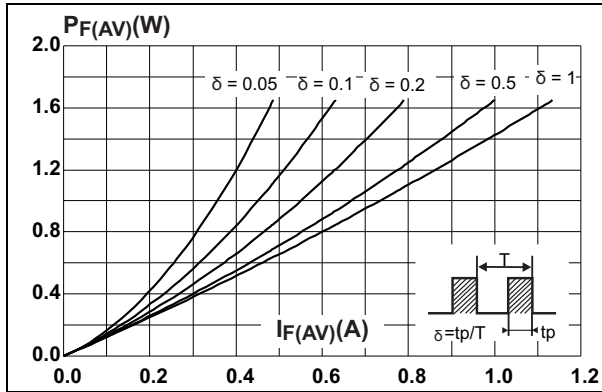
**Table 5. Dynamic electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
t <sub>rr</sub>	Reverse recovery time	T <sub>j</sub> = 25 °C I <sub>F</sub> = 0.5 A I <sub>rr</sub> = 0.25 A I <sub>R</sub> = 1 A		52	75	ns
t <sub>fr</sub>	Forward recovery time	T <sub>j</sub> = 25 °C I <sub>F</sub> = 1 A dI <sub>F</sub> /dt = 50 A/μs V <sub>FR</sub> = 2.70 V			300	
V <sub>FP</sub>	Forward recovery voltage				10	15

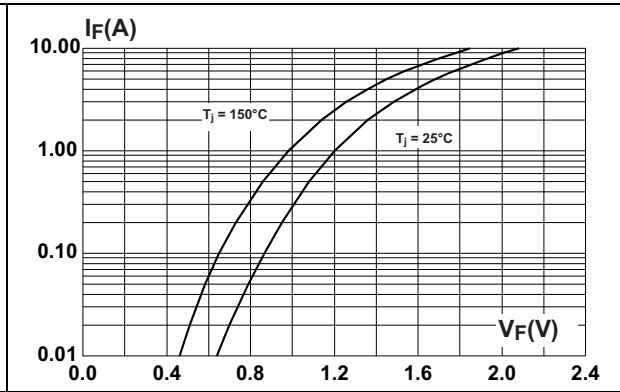
**STTH110-Y**

**Characteristics**

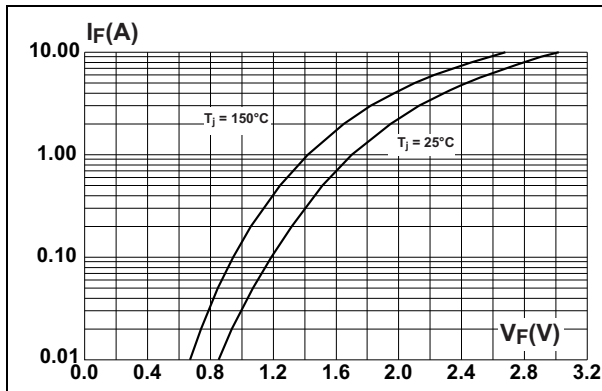
**Figure 1. Average forward power dissipation versus average forward current**



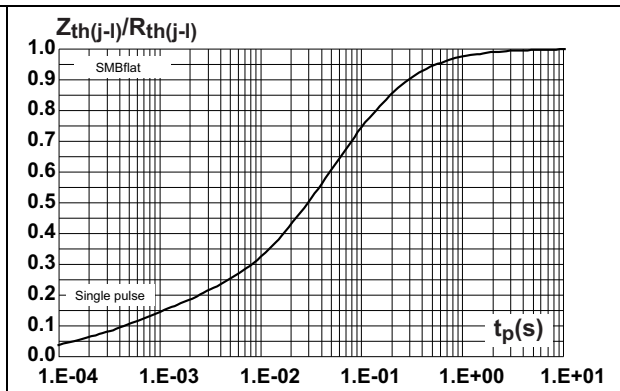
**Figure 2. Forward voltage drop versus forward current (typical values)**



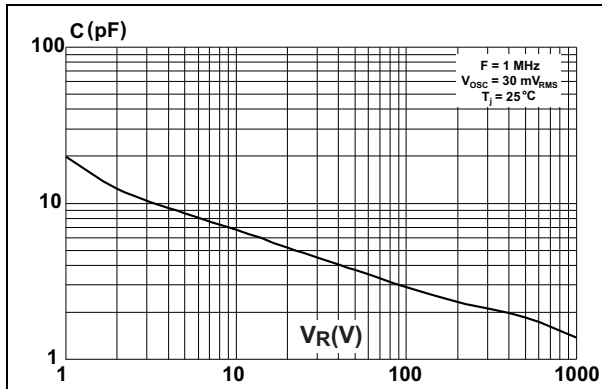
**Figure 3. Forward voltage drop versus forward current (maximum values)**



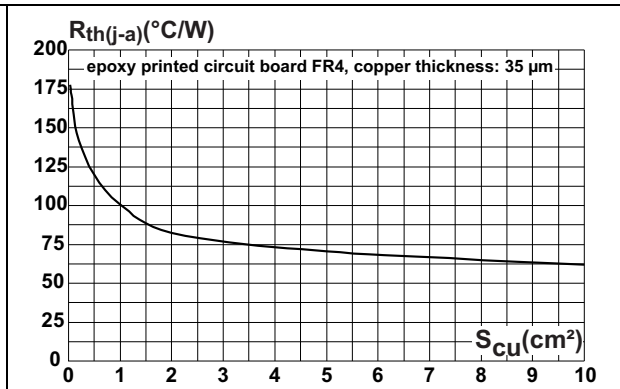
**Figure 4. Relative variation of thermal impedance junction to lead versus pulse duration**



**Figure 5. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 6. Thermal resistance junction to ambient versus copper surface under each lead**

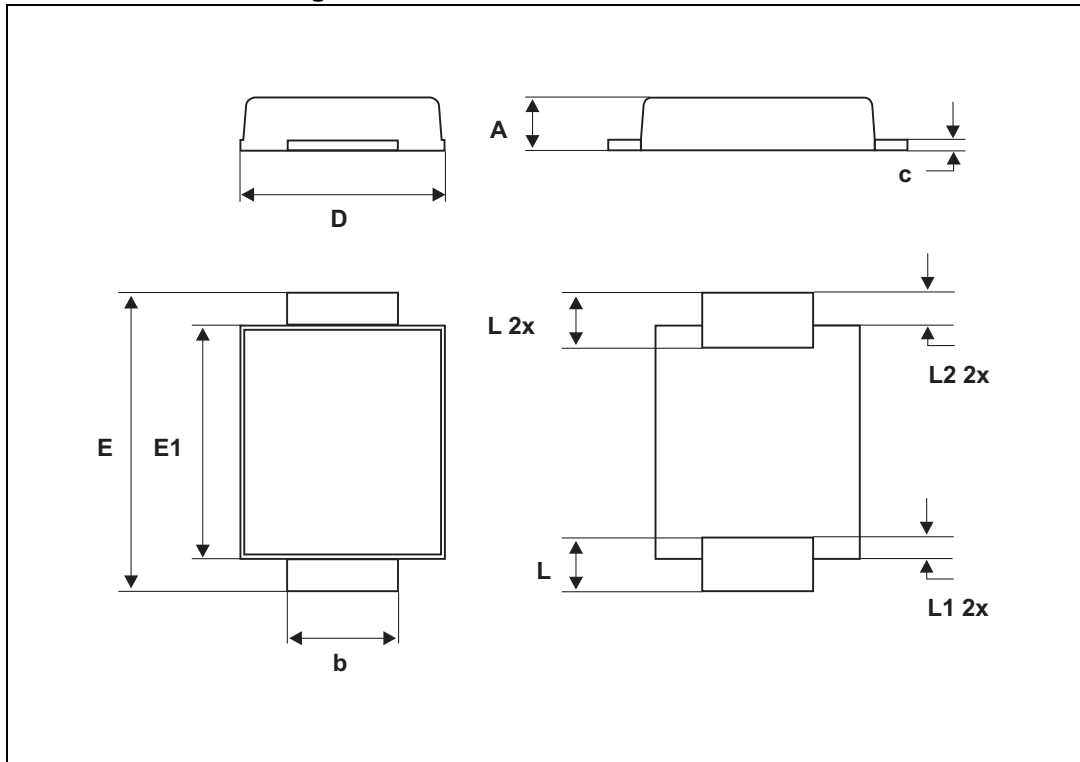


## 2 Package information

- Epoxy meets UL94,V0
- Lead-free package
- Band indicates cathode

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

**Figure 7. SMBflat dimensions definitions**



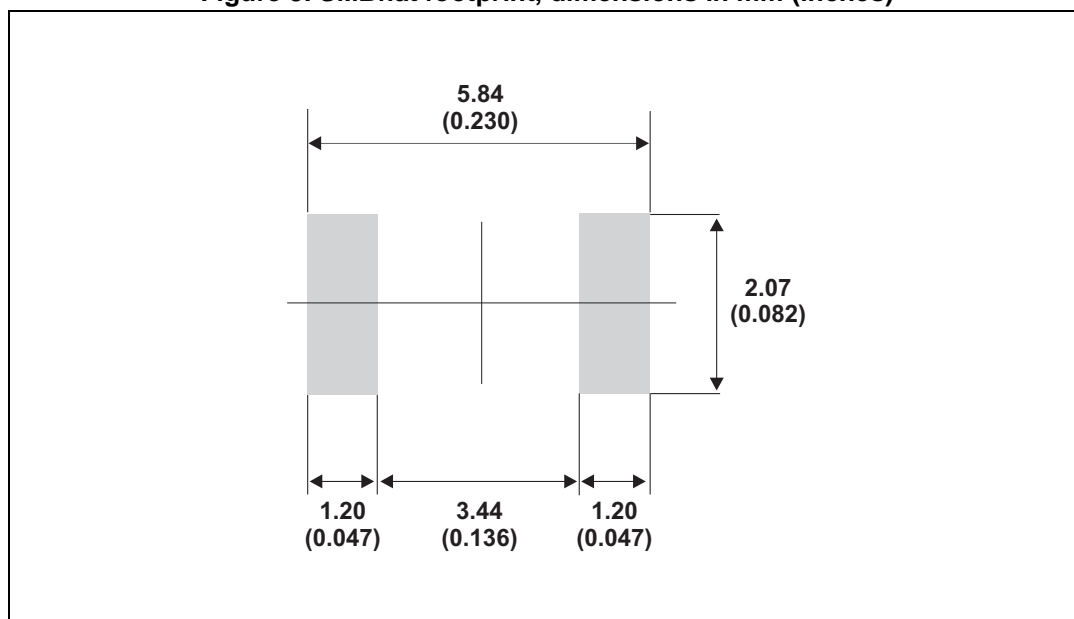
**STTH110-Y**

**Package information**

**Table 6. SMBflat dimension values**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
c	0.15		0.40	0.006		0.016
D	3.30		3.95	1.30		0.156
E	5.10		5.60	0.200		0.220
E1	4.05		4.60	0.189		0.181
L	0.75		1.50	0.029		0.059
L1		0.40			0.016	
L2		0.60			0.024	

**Figure 8. SMBflat footprint, dimensions in mm (inches)**



### 3 Ordering information

Table 7. Ordering information

Order codes	Marking	Package	Weight	Base qty	Delivery mode
STTH110UFY	F110Y	SMBflat	50 mg	5000	Tape and reel

### 4 Revision history

Table 8. Document revision history

Date	Revision	Changes
05-Feb-2014	1	Initial release.

## STTH110-Y

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